

Discription

The ESD5302F protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.



Features

Stand-off voltage: 5V Max

 Transient protection for each line according to IEC61000-4-2 (ESD): ±20kV (contact and air discharge)

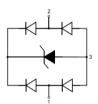
IEC61000-4-4 (EFT): 40A (5/50ns) IEC61000-4-5 (surge): 4A (8/20µs)

• Ultra-low capacitance: C_J = 0.4pF typ.

Ultra-low leakage current: I_R <1nA typ.

Low clamping voltage: V_{CL} = 20V @ I_{PP} = 16A(TLP)

Solid-state silicon technology



Circuit Diagram

Ordering Information

Product ID	Pack	Qty(PCS)
ESD5302F	SOT-23	3000

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units	
P _{PP}	Peak Pulse Power (t _p = 8/20μs)	60	W	
TL	Maximum lead temperature for soldering during 10s		260	°C
T_{stg}	Storage Temperature Range		-55 to +150	°C
T _{op}	Operating Temperature Range		-40 to +125	°C
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD) air disch contact disch		±20 ±20	KV



Electrical characteristics (T_A=25 °C, unless otherwise noted)

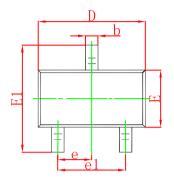
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Reverse maximum working voltage	V _{RWM}				5.0	V
Reverse leakage current	I _R	V _{RWM} = 5V		<1	100	nA
Reverse breakdown voltage	V_{BR}	I _T = 1mA	7.0	8.0	9.0	V
Forward voltage	V _F	I _T = 10mA	0.6	0.9	1.2	V
Clamping voltage 1)	V _{CL}	I _{PP} = 16A, t _p = 100ns		20		V
Dynamic resistance 1)	R _{DYN}			0.65		Ω
Q1	V _{CL}	$I_{PP} = 1A, t_p = 8/20 \mu s$			11	V
Clamping voltage ²⁾		$I_{PP} = 4A, t_p = 8/20 \mu s$			15	V
Junction capacitance	CJ	V _R = 0V, f = 1MHz Any I/O pin to GND		0.40	0.65	pF
		V _R = 0V, f = 1MHz Between any I/O pin		0.25	0.40	pF

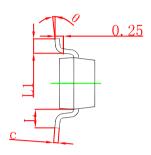
Notes:

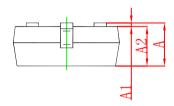
¹⁾ TLP parameter: $Z_0 = 50 \Omega$, $t_p = 100$ ns, $t_r = 2$ ns, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.

²⁾ According to IEC61000-4-5.

SOT-23 Package Outline Dimensions

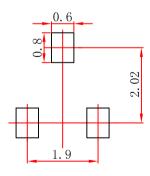






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



- Note: 1.Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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